



**PATENT**

#10/c 8/14/02  
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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Application of:**

Cobbley et al.

**Serial No.:** 09/639,486

**Filed:** August 14, 2000

**For:** METHOD OF ATTACHING SOLDER  
BALLS TO BGA PACKAGE UTILIZING A  
TOOL TO PICK AND DIP THE SOLDER  
BALL IN FLUX

**Examiner:** Z. Pittman

**Group Art Unit:** 1725

**Attorney Docket No.:** 3636.1US (97-1349.1)

**NOTICE OF EXPRESS MAILING**

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**AMENDMENT**

Box RCE  
Commissioner for Patents  
Washington, D.C. 20231

Sir:

This amendment is in response to the Final Office Action of May 9, 2002, whose initial period of response is set to expire on August 9, 2002 and the Advisory Action of July 17, 2002.

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